



**描述 / Descriptions**

Surface Mount Superfast Recovery Rectifier,Reverse Voltage:800V,Forward Current:2.0A, SMB package.

**特征 / Features**

Glass Passivated Chip Superfast reverse recovery time, Lead free in comply with EU R0HS 2011/65/EU directives,For surface mounted applications,Halogen free product.

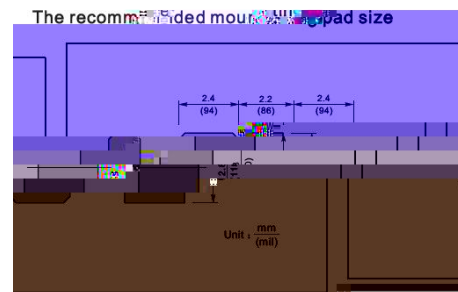
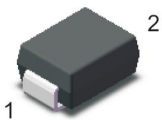
**用途 / Applications**

General purpose.

**内部等效电路 / Equivalent Circuit**



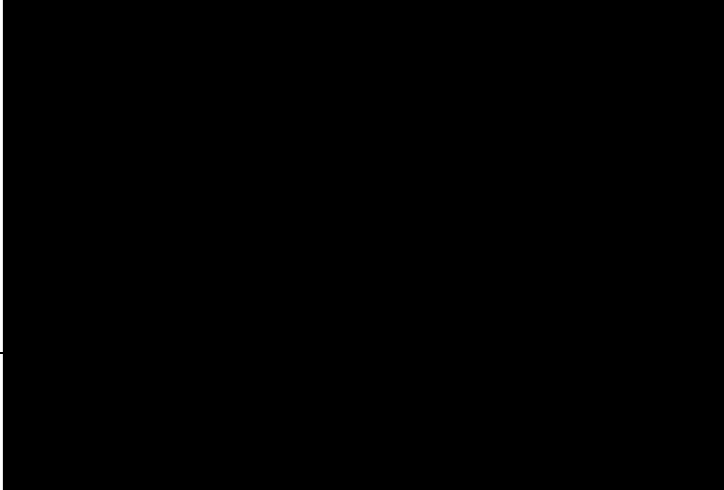
**引脚排列 / Pinning**



**印章代码 / Marking**

See Marking Instructions

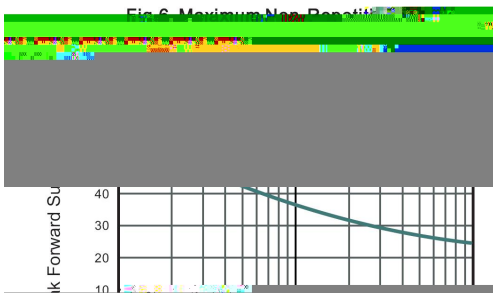
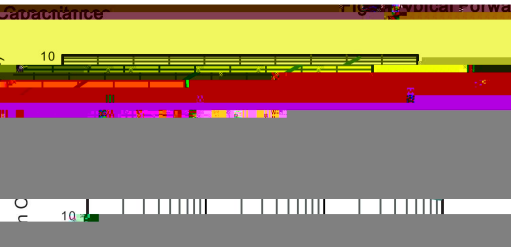
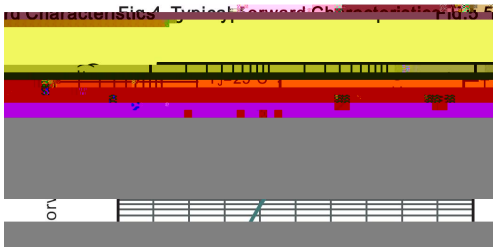
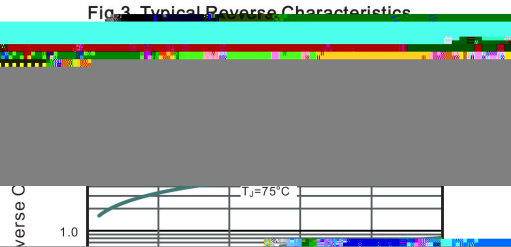
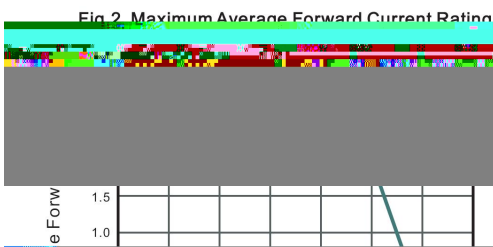
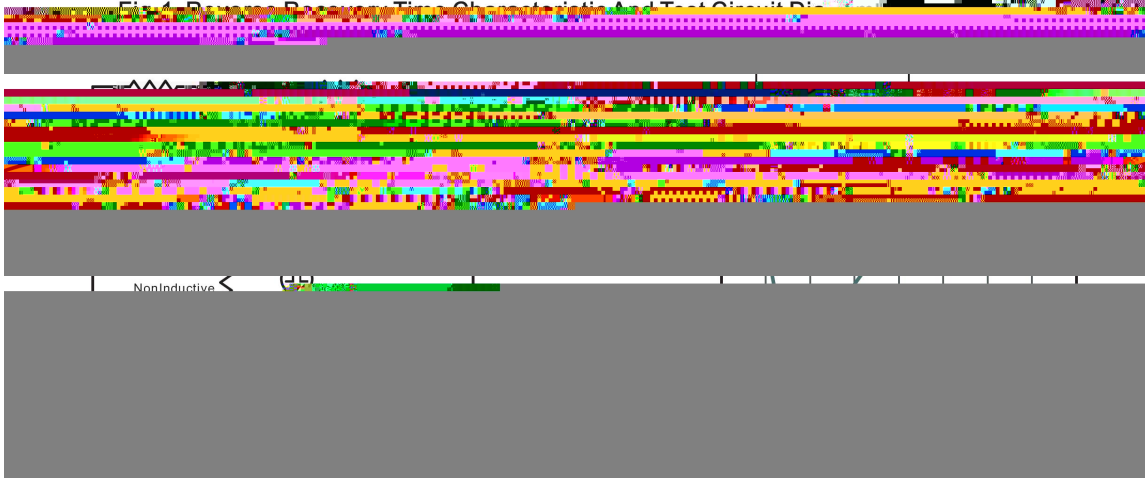
参数 Parameter	符号 Symbol
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$



80

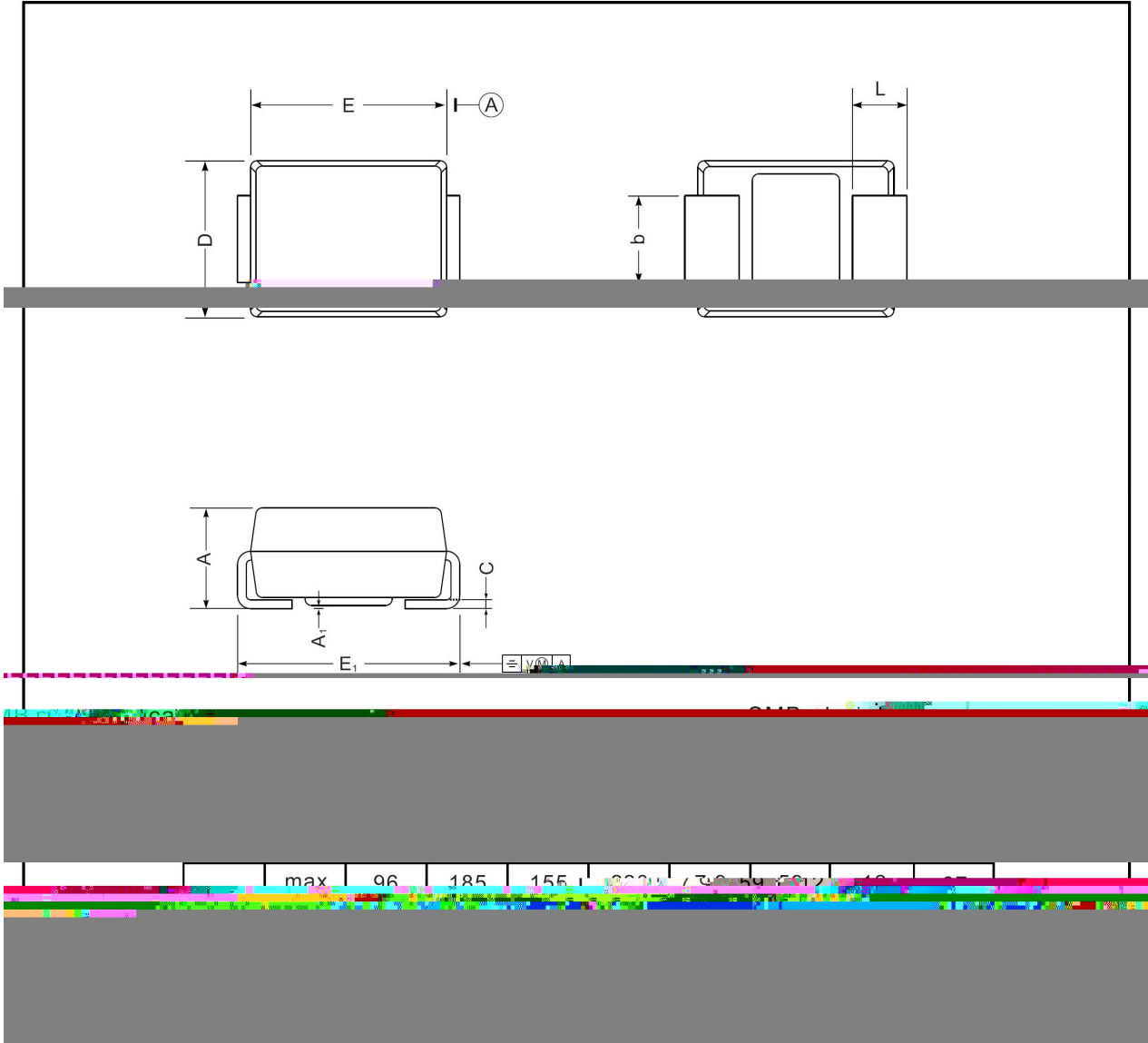


电参数曲线图 / Electrical Characteristic Curve

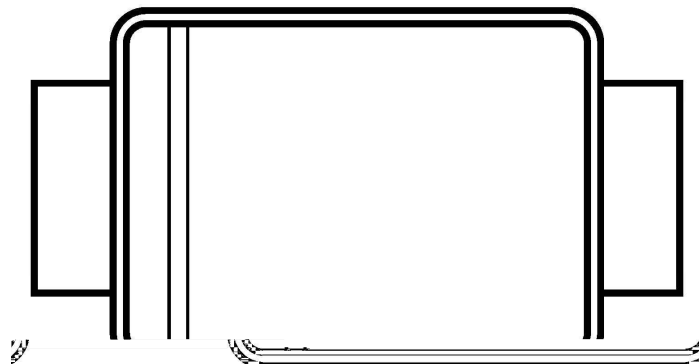


外形尺寸图 / Package Dimensions

SMB



印章说明 / Marking Instructions



说明：

ES2K： 为型号代码

\*\*\*\*： 为生产批号追溯码，第1个\*为年月代码，后面3个\*为当月小批号代码

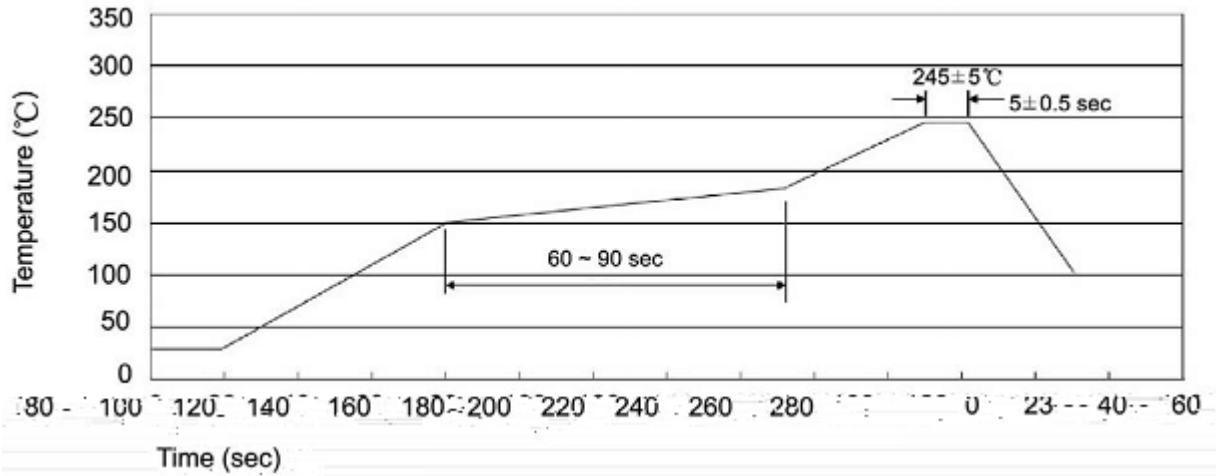
Note:

ES2K： Product Type Code

\*\*\*\*： Lot No. Code ,The 1st \* means:YM Code ,The last 3 \* means:little Lot No



回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |            |           |   |
|---|------------|-----------|---|
| 1 | 25 150     | 60 90sec; | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5      | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | 2 10 /sec. |           | 3. Cooling Speed: 2~10 /sec.            |

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

包装规格 / Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMB	3000	5	15000	5	75000	7" x11	185X180X105	390X385X205

使用说明 / Notices